CUI DEVICES

MODEL: HSS11-B20-P38 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- solder pin
- aluminum alloy
- black anodized finish

RoHS

MODEL

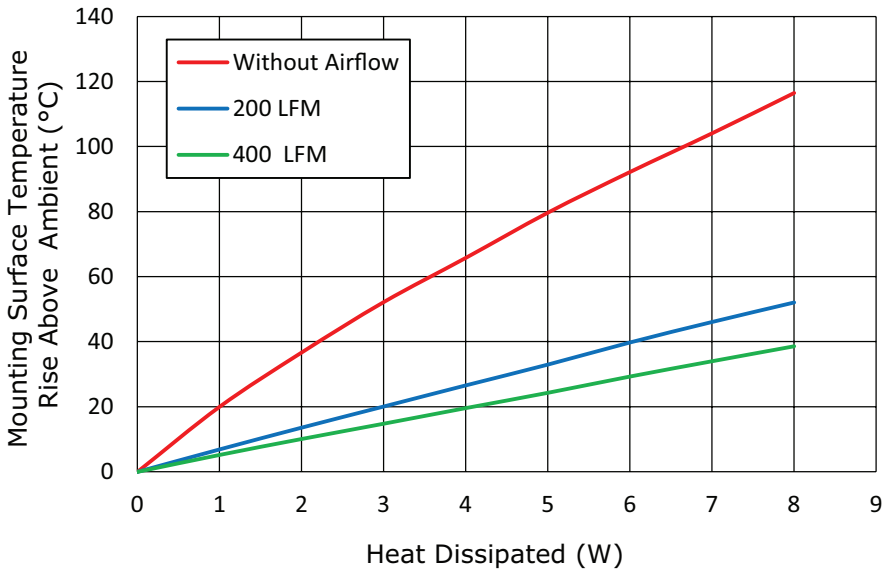
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	**@ 1 W, nat conv** (°C/W)	**@ 1 W, 200 LFM** (°C/W)	**@ 1 W, 400 LFM** (°C/W)	**@ 75°C ΔT, nat conv** (W)
HSS11-B20-P38	15.76	20.0	6.9	5.2	4.76

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	20.0	6.9	5.2
2	36.7	13.6	10.1
3	52.2	20.1	14.8
4	65.8	26.6	19.6
5	79.7	33.0	24.3
6	92.2	39.8	29.3
7	104.1	46.1	34.0
8	116.5	52.1	38.6

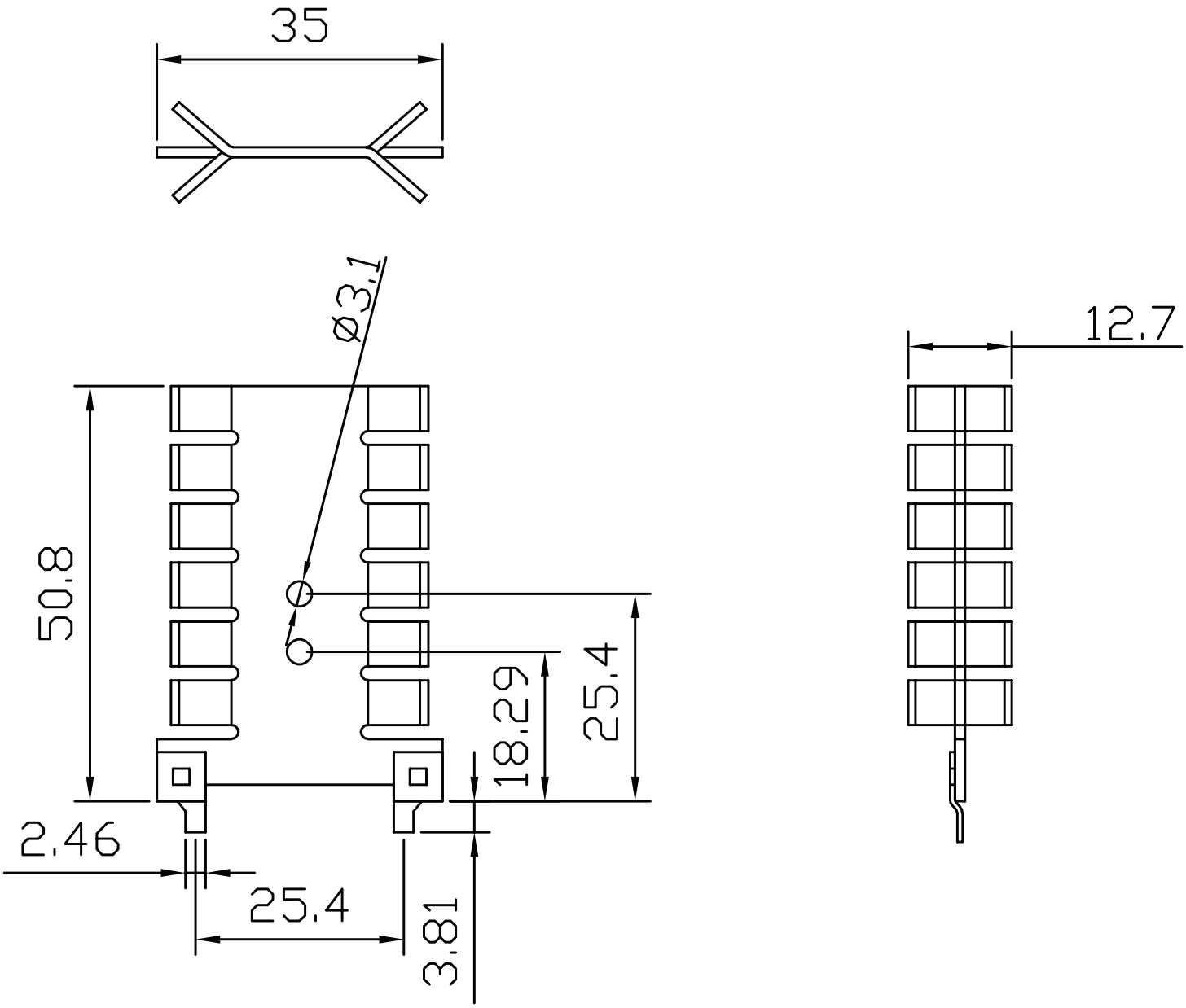
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 1050
FINISH	black anodized
THICKNESS	1.2 mm
PIN MATERIAL	brass
PIN PLATING	2~3 µm tin
WEIGHT	5.3 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/25/2021

The revision history provided is for informational purposes only and is believed to be accurate.